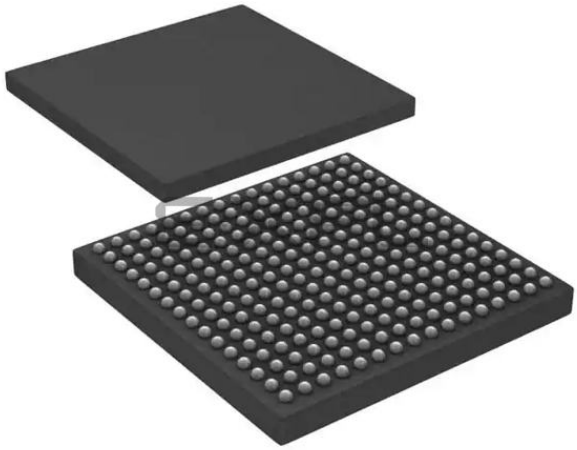

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4/M0
Core Size	32-Bit Dual-Core
Speed	204MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, IrDA, Microwire, QEI, SD, SPI, SSI, SSP, UART/USART, USB, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, LCD, Motor Control PWM, POR, PWM, WDT
Number of I/O	164
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	16K x 8
RAM Size	136K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 3.6V
Data Converters	A/D 8x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	256-LBGA
Supplier Device Package	256-LBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc4353fet256-551

- Cortex-M0 Processor core
  - ARM Cortex-M0 co-processor (version r0p0) capable of off-loading the main ARM Cortex-M4 application processor.
  - Running at frequencies of up to 204 MHz.
  - JTAG
  - Built-in NVIC.
- On-chip memory
  - Up to 1 MB on-chip dual bank flash memory with flash accelerator.
  - 16 kB on-chip EEPROM data memory.
  - 136 kB SRAM for code and data use.
  - Multiple SRAM blocks with separate bus access. Two SRAM blocks can be powered down individually.
  - 64 kB ROM containing boot code and on-chip software drivers.
  - 64 bit+ 256 bit of One-Time Programmable (OTP) memory for general-purpose use.
- Configurable digital peripherals
  - Serial GPIO (SGPIO) interface.
  - State Configurable Timer (SCTimer/PWM) subsystem on AHB.
  - Global Input Multiplexer Array (GIMA) allows to cross-connect multiple inputs and outputs to event driven peripherals like the timers, SCTimer/PWM, and ADC0/1.
- Serial interfaces
  - Quad SPI Flash Interface (SPIFI) with four lanes and up to 52 MB per second.
  - 10/100T Ethernet MAC with RMII and MII interfaces and DMA support for high throughput at low CPU load. Support for IEEE 1588 time stamping/advanced time stamping (IEEE 1588-2008 v2).
  - One High-speed USB 2.0 Host/Device/OTG interface with DMA support and on-chip high-speed PHY.
  - One High-speed USB 2.0 Host/Device interface with DMA support, on-chip full-speed PHY and ULPI interface to external high-speed PHY.
  - USB interface electrical test software included in ROM USB stack.
  - One 550 UART with DMA support and full modem interface.
  - Three 550 USARTs with DMA and synchronous mode support and a smart card interface conforming to ISO7816 specification. One USART with IrDA interface.
  - Up to two C_CAN 2.0B controllers with one channel each.
  - Two SSP controllers with FIFO and multi-protocol support. Both SSPs with DMA support.
  - One SPI controller.
  - One Fast-mode Plus I^2C-bus interface with monitor mode and with open-drain I/O pins conforming to the full I^2C-bus specification. Supports data rates of up to 1 Mbit/s.
  - One standard I^2C-bus interface with monitor mode and with standard I/O pins.
  - Two I^2S interfaces, each with DMA support and with one input and one output.
- Digital peripherals
  - External Memory Controller (EMC) supporting external SRAM, ROM, NOR flash, and SDRAM devices.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
P6_0	M12	H7	105	73	[2]	N; PU	-	**R —** Function reserved.
							O	**I2S0_RX_MCLK —** I2S receive master clock.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**I2S0_RX_SCK —** Receive Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the *I²S-bus specification*.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P6_1	R15	G5	107	74	[2]	N; PU	I/O	**GPIO3[0] —** General purpose digital input/output pin.
							O	**EMC_DYCS1 —** SDRAM chip select 1.
							I/O	**U0_UCLK —** Serial clock input/output for USART0 in synchronous mode.
							I/O	**I2S0_RX_WS —** Receive Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the *I²S-bus specification*.
							-	**R —** Function reserved.
							I	**T2_CAP0 —** Capture input 2 of timer 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P6_2	L13	J9	111	78	[2]	N; PU	I/O	**GPIO3[1] —** General purpose digital input/output pin.
							O	**EMC_CKEOUT1 —** SDRAM clock enable 1.
							I/O	**U0_DIR —** RS-485/EIA-485 output enable/direction control for USART0.
							I/O	**I2S0_RX_SDA —** I2S Receive data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the *I²S-bus specification*.
							-	**R —** Function reserved.
							I	**T2_CAP1 —** Capture input 1 of timer 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
P6_7	J13	-	123	85	[2]	N; PU	-	**R —** Function reserved.
							I/O	**EMC_A15 —** External memory address line 15.
							I/O	**SGPIO6 —** General purpose digital input/output pin.
							O	**USB0_IND1 —** USB0 port indicator LED control output 1.
							I/O	**GPIO5[15] —** General purpose digital input/output pin.
							O	**T2_MAT0 —** Match output 0 of timer 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P6_8	H13	-	125	86	[2]	N; PU	-	**R —** Function reserved.
							I/O	**EMC_A14 —** External memory address line 14.
							I/O	**SGPIO7 —** General purpose digital input/output pin.
							O	**USB0_IND0 —** USB0 port indicator LED control output 0.
							I/O	**GPIO5[16] —** General purpose digital input/output pin.
							O	**T2_MAT1 —** Match output 1 of timer 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P6_9	J15	F8	139	97	[2]	N; PU	I/O	**GPIO3[5] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**$\overline{\text{EMC\_DYCS0}}$ —** SDRAM chip select 0.
							-	**R —** Function reserved.
							O	**T2_MAT2 —** Match output 2 of timer 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P6_10	H15	-	142	100	[2]	N; PU	I/O	**GPIO3[6] —** General purpose digital input/output pin.
							O	**$\overline{\text{MCABORT}}$ —** Motor control PWM, LOW-active fast abort.
							-	**R —** Function reserved.
							O	**EMC_DQMOUT1 —** Data mask 1 used with SDRAM and static devices.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
P8_6	K3	-	43	-	[2]	N; PU	I/O	**GPIO4[6] —** General purpose digital input/output pin.
							I	**USB1_ULPI_NXT —** ULPI link NXT signal. Data flow control signal from the PHY.
							-	**R —** Function reserved.
							O	**LCD_VD5 —** LCD data.
							O	**LCD_LP —** Line synchronization pulse (STN). Horizontal synchronization pulse (TFT).
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**T0_CAP2 —** Capture input 2 of timer 0.
P8_7	K1	-	45	-	[2]	N; PU	I/O	**GPIO4[7] —** General purpose digital input/output pin.
							O	**USB1_ULPI_STP —** ULPI link STP signal. Asserted to end or interrupt transfers to the PHY.
							-	**R —** Function reserved.
							O	**LCD_VD4 —** LCD data.
							O	**LCD_PWR —** LCD panel power enable.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**T0_CAP3 —** Capture input 3 of timer 0.
P8_8	L1	-	49	-	[2]	N; PU	-	**R —** Function reserved.
							I	**USB1_ULPI_CLK —** ULPI link CLK signal. 60 MHz clock generated by the PHY.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**CGU_OUT0 —** CGU spare clock output 0.
							O	**I2S1_TX_MCLK —** I2S1 transmit master clock.
P9_0	T1	-	59	-	[2]	N; PU	I/O	**GPIO4[12] —** General purpose digital input/output pin.
							O	**$\overline{\text{MCABORT}}$ —** Motor control PWM, LOW-active fast abort.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**ENET_CRS —** Ethernet Carrier Sense (MII interface).
							I/O	**SGPIO0 —** General purpose digital input/output pin.
							I/O	**SSP0_SSEL —** Slave Select for SSP0.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
P9_5	M9	-	98	69	[2]	N; PU	-	**R —** Function reserved.
							O	**MCOA1 —** Motor control PWM channel 1, output A.
							O	**USB1_PPWR —** VBUS drive signal (towards external charge pump or power management unit); indicates that VBUS must be driven (active high). Add a pull-down resistor to disable the power switch at reset. This signal has opposite polarity compared to the USB_PPWR used on other NXP LPC parts.
							-	**R —** Function reserved.
							I/O	**GPIO5[18] —** General purpose digital input/output pin.
							O	**ENET_TXD3 —** Ethernet transmit data 3 (MII interface).
							I/O	**SGPIO3 —** General purpose digital input/output pin.
							O	**U0_TXD —** Transmitter output for USART0.
P9_6	L11	-	103	72	[2]	N; PU	I/O	**GPIO4[11] —** General purpose digital input/output pin.
							O	**MCOB1 —** Motor control PWM channel 1, output B.
							I	**USB1_PWR_FAULT —** USB1 Port power fault signal indicating over-current condition; this signal monitors over-current on the USB1 bus (external circuitry required to detect over-current condition).
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**ENET_COL —** Ethernet Collision detect (MII interface).
							I/O	**SGPIO8 —** General purpose digital input/output pin.
							I	**U0_RXD —** Receiver input for USART0.
PA_0	L12	-	126	-	[2]	N; PU	-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**I2S1_RX_MCLK —** I2S1 receive master clock.
							O	**CGU_OUT1 —** CGU spare clock output 1.
							-	**R —** Function reserved.
PA_1	J14	-	134	-	[3]	N; PU	I/O	**GPIO4[8] —** General purpose digital input/output pin.
							I	**QEI_IDX —** Quadrature Encoder Interface INDEX input.
							-	**R —** Function reserved.
							O	**U2_TXD —** Transmitter output for USART2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
WAKEUP0	A9	A4	187	130	[11]	I; IA	I	External wake-up input; can raise an interrupt and can cause wake-up from any of the low power modes. A pulse with a duration of at least 45 ns wakes up the part. Input 0 of the event monitor.No internal pull-up is enabled when this pin is configured as input.
WAKEUP1	A10	-	-	-	[11]	I; IA	I	External wake-up input; can raise an interrupt and can cause wake-up from any of the low power modes. A pulse with a duration of at least 45 ns wakes up the part. Input 1 of the event monitor. No internal pull-up is enabled when this pin is configured as input.
WAKEUP2	C9	-	-	-	[11]	I; IA	I	External wake-up input; can raise an interrupt and can cause wake-up from any of the low power modes. A pulse with a duration of at least 45 ns wakes up the part. Input 2 of the event monitor. This pin does not have an internal pull-up.
WAKEUP3	D8	-	-	-	[11]	I; IA	I	External wake-up input; can raise an interrupt and can cause wake-up from any of the low power modes. A pulse with a duration of at least 45 ns wakes up the part. This pin does not have an internal pull-up.
ADC pins								
ADC0_0/ ADC1_0/DAC	E3	A2	8	6	[8]	I; IA	I	ADC input channel 0. Shared between 10-bit ADC0/1 and DAC.
ADC0_1/ ADC1_1	C3	A1	4	2	[8]	I; IA	I	ADC input channel 1. Shared between 10-bit ADC0/1.
ADC0_2/ ADC1_2	A4	B3	206	143	[8]	I; IA	I	ADC input channel 2. Shared between 10-bit ADC0/1.
ADC0_3/ ADC1_3	B5	A3	200	139	[8]	I; IA	I	ADC input channel 3. Shared between 10-bit ADC0/1.
ADC0_4/ ADC1_4	C6	-	199	138	[8]	I; IA	I	ADC input channel 4. Shared between 10-bit ADC0/1.
ADC0_5/ ADC1_5	B3	-	208	144	[8]	I; IA	I	ADC input channel 5. Shared between 10-bit ADC0/1.
ADC0_6/ ADC1_6	A5	-	204	142	[8]	I; IA	I	ADC input channel 6. Shared between 10-bit ADC0/1.
ADC0_7/ ADC1_7	C5	-	197	136	[8]	I; IA	I	ADC input channel 7. Shared between 10-bit ADC0/1.
RTC								
RTC_ALARM	A11	C3	186	129	[11]	-	O	RTC controlled output.
RTCX1	A8	A5	182	125	[8]	-	I	Input to the RTC 32 kHz ultra-low power oscillator circuit.
RTCX2	B8	B5	183	126	[8]	-	O	Output from the RTC 32 kHz ultra-low power oscillator circuit.
$\overline{\text{SAMPLE}}$	B9	-	-	-	[11]	O	O	Event monitor sample output.
Crystal oscillator pins								

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
VSS	G9, H7, J10, J11, K8	C8, D4, D5, G8, J3, J6	-	-	[13]	-	-	Ground.
VSSIO	C4, D13, G6, G7, G8, H8, H9, J8, J9, K9, K10, M13, P7, P13	-	5, 56, 109, 157	4, 40, 76, 109	[13]	-	-	Ground.
VSSA	B2	C2	196	135		-	-	Analog ground.

[1] N = neutral, input buffer disabled; no extra VDDIO current consumption if the input is driven midway between supplies; set the EZI bit in the SFS register to enable the input buffer; I = input, OL = output driving LOW; OH = output driving HIGH; AI/O = analog input/output; IA = inactive; PU = pull-up enabled (weak pull-up resistor pulls up pin to VDDIO; F = floating. Reset state reflects the pin state at reset without boot code operation.

[2] 5 V tolerant pad with 15 ns glitch filter (5 V tolerant if VDDIO present; if VDDIO not present, do not exceed 3.6 V); provides digital I/O functions with TTL levels and hysteresis; normal drive strength.

[3] 5 V tolerant pad with 15 ns glitch filter (5 V tolerant if VDDIO present; if VDDIO not present, do not exceed 3.6 V); provides digital I/O functions with TTL levels, and hysteresis; high drive strength.

[4] 5 V tolerant pad with 15 ns glitch filter (5 V tolerant if VDDIO present; if VDDIO not present, do not exceed 3.6 V); provides high-speed digital I/O functions with TTL levels and hysteresis.

[5] 5 V tolerant pad providing digital I/O functions (with TTL levels and hysteresis) and analog input or output (5 V tolerant if VDDIO present; if VDDIO not present, do not exceed 3.6 V). When configured as a ADC input or DAC output, the pin is not 5 V tolerant and the digital section of the pad must be disabled by setting the pin to an input function and disabling the pull-up resistor through the pin's SFSP register.

[6] 5 V tolerant transparent analog pad.

[7] For maximum load C_L = 6.5 μF and maximum resistance R_{pd} = 80 kΩ, the VBUS signal takes about 2 s to fall from VBUS = 5 V to VBUS = 0.2 V when it is no longer driven.

[8] Transparent analog pad. Not 5 V tolerant.

[9] Pad provides USB functions; 5 V tolerant if VDDIO present; if VDDIO not present, do not exceed 3.6 V. It is designed in accordance with the USB specification, revision 2.0 (Full-speed and Low-speed mode only).

[10] Open-drain 5 V tolerant digital I/O pad, compatible with I2C-bus Fast Mode Plus specification. This pad requires an external pull-up to provide output functionality. When power is switched off, this pin connected to the I2C-bus is floating and does not disturb the I2C lines.

[11] 5 V tolerant pad with 20 ns glitch filter; provides digital I/O functions with open-drain output and hysteresis.

[12] VPP is internally connected to VDDIO for all packages with the exception of the LBGA256 package.

[13] On the LQFP208 package, VSSIO and VSS are connected to a common ground plane.

7. Functional description

7.1 Architectural overview

The ARM Cortex-M4 includes three AHB-Lite buses: the system bus, the I-CODE bus, and the D-code bus. The I-CODE and D-code core buses allow for concurrent code and data accesses from different slave ports.

The LPC435x/3x/2x/1x use a multi-layer AHB matrix to connect the ARM Cortex-M4 buses and other bus masters to peripherals in a flexible manner that optimizes performance by allowing peripherals that are on different slaves ports of the matrix to be accessed simultaneously by different bus masters.

An ARM Cortex-M0 co-processor is included in the LPC435x/3x/2x/1x, capable of off-loading the main ARM Cortex-M4 application processor. Most peripheral interrupts are connected to both processors. The processors communicate with each other via an interprocessor communication protocol.

7.2 ARM Cortex-M4 processor

The ARM Cortex-M4 CPU incorporates a 3-stage pipeline, uses a Harvard architecture with separate local instruction and data buses as well as a third bus for peripherals, and includes an internal prefetch unit that supports speculative branching. The ARM Cortex-M4 supports single-cycle digital signal processing and SIMD instructions. A hardware floating-point processor is integrated in the core. The processor includes an NVIC with up to 53 interrupts.

7.3 ARM Cortex-M0 co-processor

The ARM Cortex-M0 is a general purpose, 32-bit microprocessor, which offers high performance and very low power consumption. The ARM Cortex-M0 co-processor uses a 3-stage pipeline von Neumann architecture and a small but powerful instruction set providing high-end processing hardware. In LPC43xx, the Cortex-M0 coprocessor hardware multiply is implemented as a 32-cycle iterative multiplier. The co-processor incorporates an NVIC with 32 interrupts.

7.4 Interprocessor communication

The ARM Cortex-M4 and ARM Cortex-M0 interprocessor communication is based on using shared SRAM as mailbox and one processor raising an interrupt on the other processor's NVIC, for example after it has delivered a new message in the mailbox. The receiving processor can reply by raising an interrupt on the sending processor's NVIC to acknowledge the message.

7.15 One-Time Programmable (OTP) memory

The OTP provides 64 bit+ 256 bit of memory for general-purpose use.

7.16 General Purpose I/O (GPIO)

The LPC435x/3x/2x/1x provide eight GPIO ports with up to 31 GPIO pins each.

Device pins that are not connected to a specific peripheral function are controlled by the GPIO registers. Pins may be dynamically configured as inputs or outputs. Separate registers allow setting or clearing any number of outputs simultaneously. The value of the output register may be read back as well as the current state of the port pins.

All GPIO pins default to inputs with pull-up resistors enabled and input buffer disabled on reset. The input buffer must be turned on in the system control block SFS register before the GPIO input can be read.

7.16.1 Features

- Accelerated GPIO functions:
  - GPIO registers are located on the AHB so that the fastest possible I/O timing can be achieved.
  - Mask registers allow treating sets of port bits as a group, leaving other bits unchanged.
  - All GPIO registers are byte and half-word addressable.
  - Entire port value can be written in one instruction.
- Bit-level set and clear registers allow a single instruction set or clear of any number of bits in one port.
- Direction control of individual bits.
- Up to eight GPIO pins can be selected from all GPIO pins to create an edge- or level-sensitive GPIO interrupt request (GPIO interrupts).
- Two GPIO group interrupts can be triggered by any pin or pins in each port (GPIO group0 and group1 interrupts).

7.17 Configurable digital peripherals

7.17.1 State Configurable Timer (SCTimer/PWM) subsystem

The SCTimer/PWM allows a wide variety of timing, counting, output modulation, and input capture operations. The inputs and outputs of the SCTimer/PWM are shared with the capture and match inputs/outputs of the 32-bit general purpose counter/timers.

The SCTimer/PWM can be configured as two 16-bit counters or a unified 32-bit counter. In the two-counter case, in addition to the counter value the following operational elements are independent for each half:

- State variable
- Limit, halt, stop, and start conditions
- Values of Match/Capture registers, plus reload or capture control values

7.19.6.1 Features

- The I^2S interfaces has separate input/output channels, each of which can operate in master or slave mode.
- Capable of handling 8-bit, 16-bit, and 32-bit word sizes.
- Mono and stereo audio data supported.
- The sampling frequency can range from 16 kHz to 192 kHz (16, 22.05, 32, 44.1, 48, 96, 192) kHz.
- Support for an audio master clock.
- Configurable word select period in master mode (separately for I^2S-bus input and output).
- Two 8-word FIFO data buffers are provided, one for transmit and one for receive.
- Generates interrupt requests when buffer levels cross a programmable boundary.
- Two DMA requests controlled by programmable buffer levels. The DMA requests are connected to the GPDMA block.
- Controls include reset, stop and mute options separately for I^2S-bus input and I^2S-bus output.

7.19.7 C_CAN

Remark: The LPC435x/3x/2x/1x each contain two C_CAN controllers.

Controller Area Network (CAN) is the definition of a high performance communication protocol for serial data communication. The C_CAN controller is designed to provide a full implementation of the CAN protocol according to the CAN Specification Version 2.0B. The C_CAN controller allows to build powerful local networks with low-cost multiplex wiring by supporting distributed real-time control with a high level of reliability.

7.19.7.1 Features

- Conforms to protocol version 2.0 parts A and B.
- Supports bit rate of up to 1 Mbit/s.
- Supports 32 Message Objects.
- Each Message Object has its own identifier mask.
- Provides programmable FIFO mode (concatenation of Message Objects).
- Provides maskable interrupts.
- Supports Disabled Automatic Retransmission (DAR) mode for time-triggered CAN applications.
- Provides programmable loop-back mode for self-test operation.

7.20 Counter/timers and motor control

7.20.1 General purpose 32-bit timers/external event counters

Remark: The LPC435x/3x/2x/1x include four 32-bit timer/counters.

7.23.2 System Control Unit (SCU)

The system control unit determines the function and electrical mode of the digital pins. By default function 0 is selected for all pins with pull-up enabled. For pins that support a digital and analog function, the ADC function select registers in the SCU enable the analog function.

A separate set of analog I/Os for the ADCs and the DAC as well as most USB pins are located on separate pads and are not controlled through the SCU.

In addition, the clock delay register for the SDRAM EMC_CLK pins and the registers that select the pin interrupts are located in the SCU.

7.23.3 Clock Generation Unit (CGU)

The Clock Generator Unit (CGU) generates several base clocks. The base clocks can be unrelated in frequency and phase and can have different clock sources within the CGU. One CGU base clock is routed to the CLKOUT pins. The base clock that generates the CPU clock is referred to as CCLK.

Multiple branch clocks are derived from each base clock. The branch clocks offer flexible control for power-management purposes. All branch clocks are outputs of one of two Clock Control Units (CCUs) and can be controlled independently. Branch clocks derived from the same base clock are synchronous in frequency and phase.

7.23.4 Internal RC oscillator (IRC)

The IRC is used as the clock source for the WWDT and/or as the clock that drives the PLLs and the CPU. The nominal IRC frequency is 12 MHz. The IRC is trimmed to 1.5 % accuracy for T_{amb} = 0 °C to 85 °C and 3% accuracy for T_{amb} = -40 °C to 0 °C and T_{amb} = 85 °C to 105 °C.

Upon power-up or any chip reset, the LPC435x/3x/2x/1x use the IRC as the clock source. The boot loader then configures the PLL1 to provide a 96 MHz clock for the core and PLL0USB or PLL0AUDIO as needed if an external boot source is selected.

7.23.5 PLL0USB (for USB0)

PLL0 is a dedicated PLL for the USB0 High-speed controller.

PLL0 accepts an input clock frequency from an external oscillator in the range of 14 kHz to 25 MHz. The input frequency is multiplied up to a high frequency with a Current Controlled Oscillator (CCO). The CCO operates in the range of 4.3 MHz to 550 MHz.

7.23.6 PLL0AUDIO (for audio)

The audio PLL PLL0AUDIO is a general purpose PLL with a very small step size. This PLL accepts an input clock frequency derived from an external oscillator or internal IRC. The input frequency is multiplied up to a high frequency with a Current Controlled Oscillator (CCO). A sigma-delta converter modulates the PLL divider ratios to obtain the desired output frequency. The output frequency can be set as a multiple of the sampling frequency f_s to $32 \times f_s$, $64 \times f_s$, $128 \times f_s$, $256 \times f_s$, $384 \times f_s$, $512 \times f_s$ and the sampling frequency f_s can range from 16 kHz to 192 kHz (16, 22.05, 32, 44.1, 48, 96,192) kHz. Many other frequencies are possible as well using the integrated fractional divider.

There are three levels of the Code Read Protection:

- In level CRP1, access to the chip via the JTAG is disabled. Partial flash updates are allowed (excluding flash sector 0) using a limited set of the ISP commands. This level is useful when CRP is required and flash field updates are needed. CRP1 does prevent the user code from erasing all sectors.
- In level CRP2, access to the chip via the JTAG is disabled. Only a full flash erase and update using a reduced set of the ISP commands is allowed.
- In level CRP3, any access to the chip via the JTAG pins or the ISP is disabled. This mode also disables the ISP override using P2_7 pin. If necessary, the application code must provide a flash update mechanism using the IAP calls or using the reinvoke ISP command to enable flash update via USART0. See Table 5.

CAUTION

If level three Code Read Protection (CRP3) is selected, no future factory testing can be performed on the device.

7.24 Serial Wire Debug/JTAG

Debug and trace functions are integrated into the ARM Cortex-M4. Serial wire debug and trace functions are supported in addition to a standard JTAG debug and parallel trace functions. The ARM Cortex-M4 is configured to support up to eight breakpoints and four watch points.

Remark: Serial Wire Debug is supported for the ARM Cortex-M4 only,

The ARM Cortex-M0 coprocessor supports JTAG debug. A standard ARM Cortex-compliant debugger can debug the ARM Cortex-M4 and the ARM Cortex-M0 cores separately or both cores simultaneously.

Remark: In order to debug the ARM Cortex-M0, release the M0 reset by software in the RGU block.

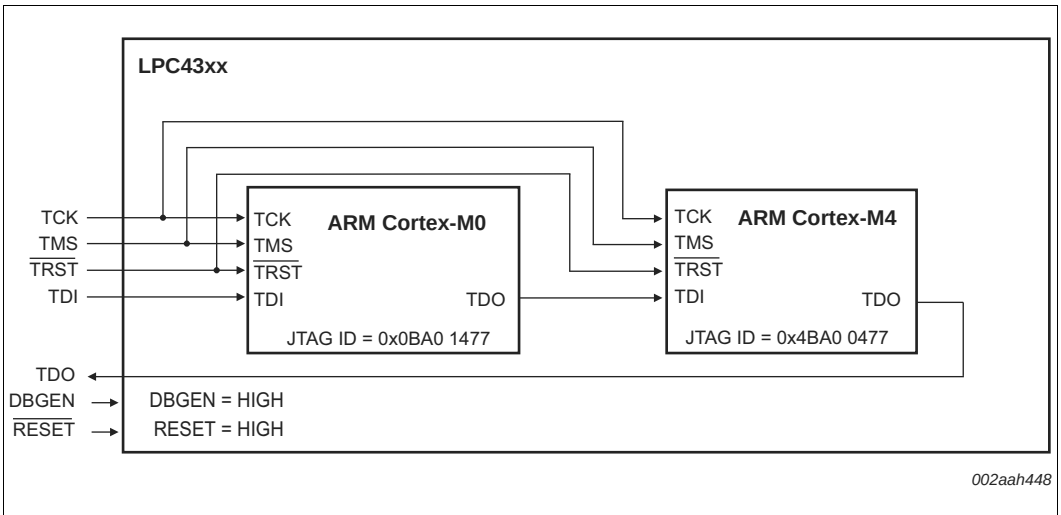
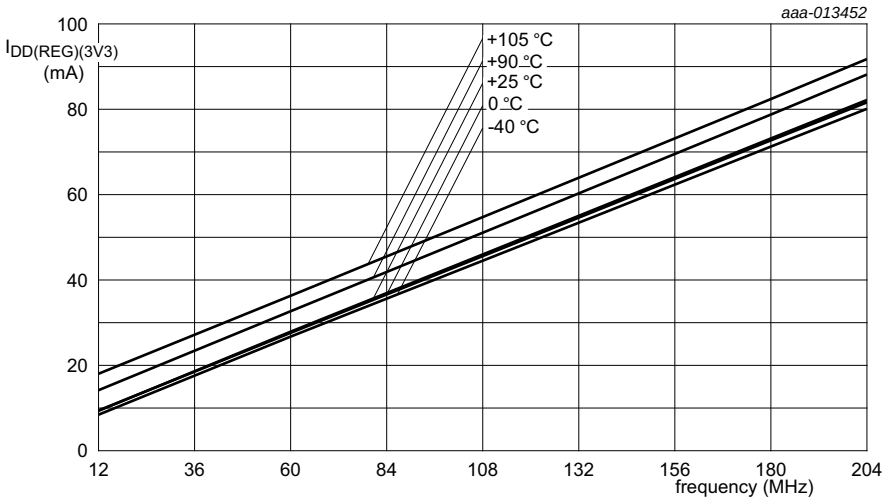
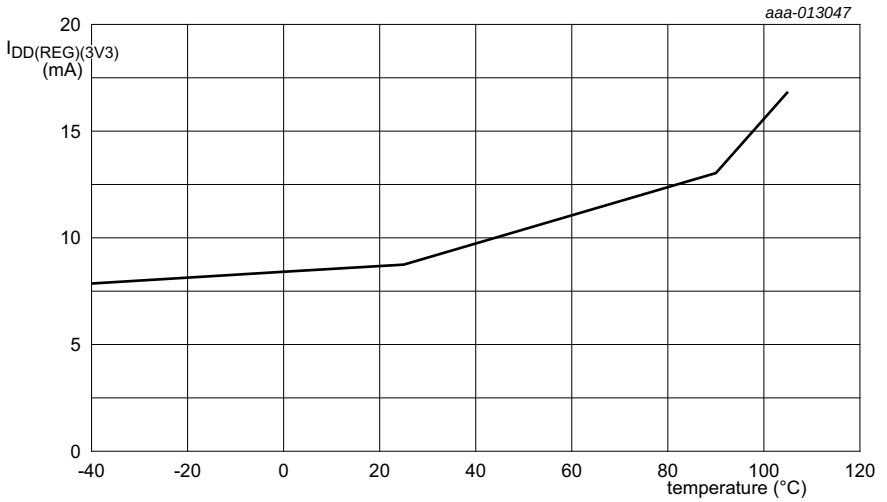


Fig 10. Dual-core debug configuration



Conditions: active mode entered executing code while (1){} from SRAM; M0 core in reset; $V_{DD(REG)(3V3)}$ = 3.3 V; system PLL enabled; IRC enabled; all peripherals disabled; all peripheral clocks disabled.

Fig 13. Typical supply current versus core frequency in active mode; code executed from SRAM



Conditions: $V_{DD(REG)(3V3)}$ = 3.3 V; internal pull-up resistors disabled; M0 core in reset; system PLL disabled; IRC enabled; all peripherals disabled; all peripheral clocks disabled. CCLK = 12 MHz.

Fig 14. Typical supply current versus temperature in sleep mode

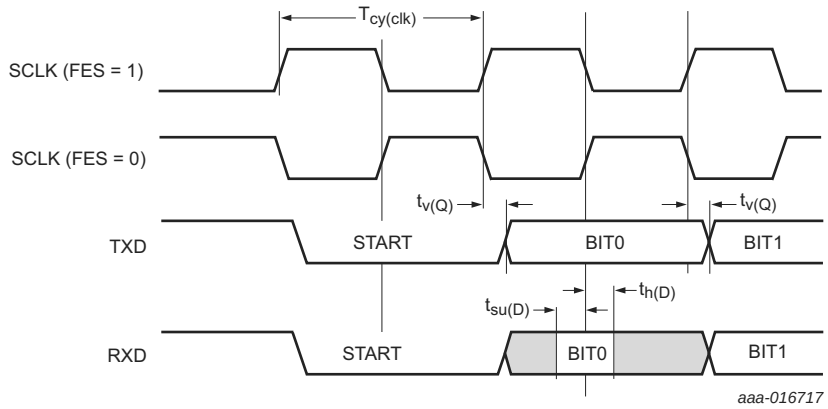


Fig 30. USART timing

11.17 External memory interface

Table 31. Dynamic characteristics: Static asynchronous external memory interface

C_L = 22 pF for EMC_Dn C_L = 20 pF for all others; T_{amb} = −40 °C to 105 °C; 2.4 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V; 2.7 V ≤ $V_{DD(IO)}$ ≤ 3.6 V; values guaranteed by design; the values in the table have been calculated with WAITTURN = 0x0 in STATICWAITTURN register. Timing parameters are given for single memory access cycles. In a normal read operation, the EMC changes the address while CS is asserted which results in multiple memory accesses.

Symbol	Parameter[1]	Conditions		Min	Typ	Max	Unit
Read cycle parameters							
t_{CSLAV}	$\overline{CS}$ LOW to address valid time			−3.1	-	1.6	ns
t_{CSLOEL}	$\overline{CS}$ LOW to $\overline{OE}$ LOW time		[2] [2]	−0.6 + $T_{cy(clk)}$ × WAITOEN	-	1.3 + $T_{cy(clk)}$ × WAITOEN	ns
$t_{CSLBLSL}$	$\overline{CS}$ LOW to $\overline{BLS}$ LOW time	PB = 1		−0.7	-	1.8	ns
t_{OELOEH}	$\overline{OE}$ LOW to $\overline{OE}$ HIGH time		[2]	−0.6 + (WAITRD − WAITOEN + 1) × $T_{cy(clk)}$	-	−0.4 + (WAITRD − WAITOEN + 1) × $T_{cy(clk)}$	ns
t_{am}	memory access time			-	-	−16 + (WAITRD − WAITOEN +1) × $T_{cy(clk)}$	ns
$t_{h(D)}$	data input hold time			−16	-	-	ns
$t_{CSHBLSH}$	$\overline{CS}$ HIGH to $\overline{BLS}$ HIGH time	PB = 1		−0.4	-	1.9	ns
t_{CSHOEH}	CS HIGH to $\overline{OE}$ HIGH time			−0.4	-	1.4	ns
t_{OEHANV}	$\overline{OE}$ HIGH to address invalid	PB = 1		−2.0	-	2.6	ns
t_{CSHEOR}	$\overline{CS}$ HIGH to end of read time		[3]	−2.0	-	0	ns
t_{CSLSOR}	$\overline{CS}$ LOW to start of read time		[4]	0	-	1.8	ns
Write cycle parameters							
t_{CSLAV}	$\overline{CS}$ LOW to address valid time			−3.1	-	1.6	ns
t_{CSLDV}	$\overline{CS}$ LOW to data valid time			−3.1	-	1.5	ns
t_{CSLWEL}	$\overline{CS}$ LOW to $\overline{WE}$ LOW time	PB = 1		−1.5 + (WAITWEN + 1) × $T_{cy(clk)}$	-	0.2 + (WAITWEN + 1) × $T_{cy(clk)}$	ns
$t_{CSLBLSL}$	$\overline{CS}$ LOW to $\overline{BLS}$ LOW time	PB = 1		−0.7	-	1.8	ns
t_{WELWEH}	$\overline{WE}$ LOW to $\overline{WE}$ HIGH time	PB = 1	[2]	−0.6 + (WAITWR − WAITWEN + 1) × $T_{cy(clk)}$	-	−0.4 + (WAITWR − WAITWEN + 1) × $T_{cy(clk)}$	ns
t_{WEHDNV}	$\overline{WE}$ HIGH to data invalid time	PB = 1	[2]	−0.9 + $T_{cy(clk)}$	-	2.3 + $T_{cy(clk)}$	ns
t_{WEHEOW}	$\overline{WE}$ HIGH to end of write time	PB = 1	[2] [5]	−0.4 + $T_{cy(clk)}$	-	−0.3 + $T_{cy(clk)}$	ns
$t_{CSLBLSL}$	$\overline{CS}$ LOW to $\overline{BLS}$ LOW	PB = 0		−0.7 + (WAITWEN + 1) × $T_{cy(clk)}$	-	1.8 + (WAITWEN + 1) × $T_{cy(clk)}$	ns

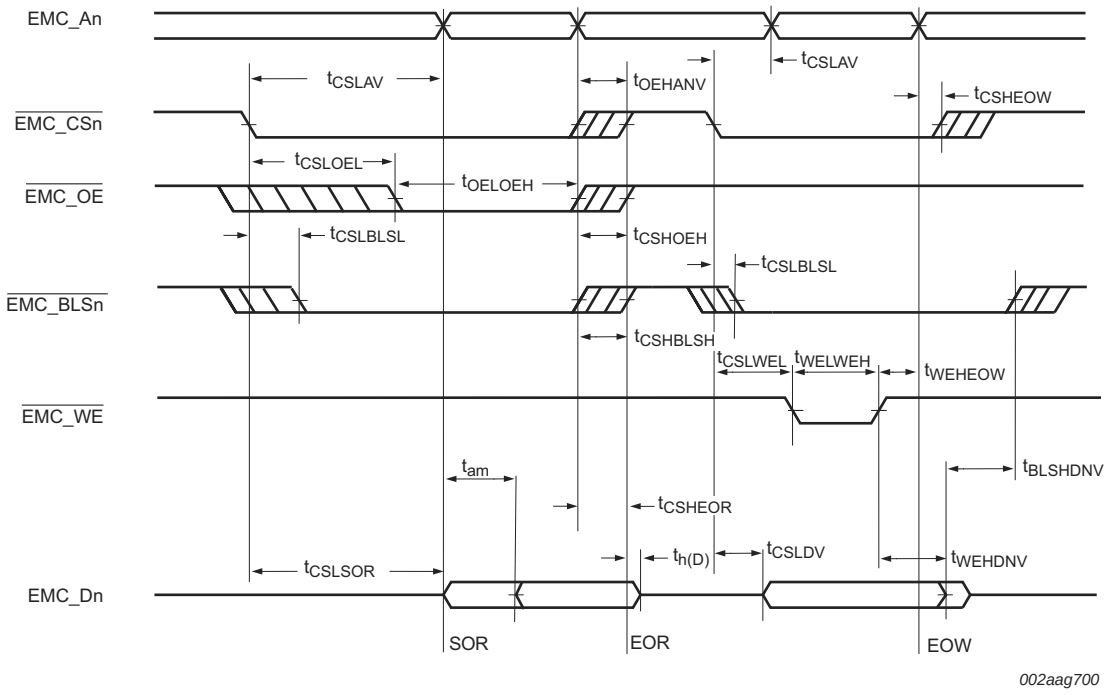


Fig 36. External static memory read/write access (PB = 1)

11.20 SD/MMC

Table 37. Dynamic characteristics: SD/MMC

T_{amb} = −40 °C to +105 °C, 2.4 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V; 2.7 V ≤ $V_{DD(IO)}$ ≤ 3.6 V, C_L = 20 pF. SAMPLE_DELAY = 0x9, DRV_DELAY = 0x6 in the SDDELAY register, sampled at 90 % and 10 % of the signal level, EHS = 1 for SD_CLK pin, EHS = 0 for SD_DATn and SD_CMD pins. Simulated values.

Symbol	Parameter	Conditions	Min	Max	Unit
f_{clk}	clock frequency	on pin SD_CLK; data transfer mode	-	52	MHz
$t_{su(D)}$	data input set-up time	on pins SD_DATn as inputs	5.2	-	ns
		on pins SD_CMD as inputs	7	-	ns
$t_{h(D)}$	data input hold time	on pins SD_DATn as inputs	0.2	-	ns
		on pins SD_CMD as inputs	−1		ns
$t_{d(QV)}$	data output valid delay time	on pins SD_DATn as outputs	-	15.7	ns
		on pins SD_CMD as outputs	-	15.9	ns
$t_{h(Q)}$	data output hold time	on pins SD_DATn as outputs	3.5	-	ns
		on pins SD_CMD as outputs	3.5	-	ns

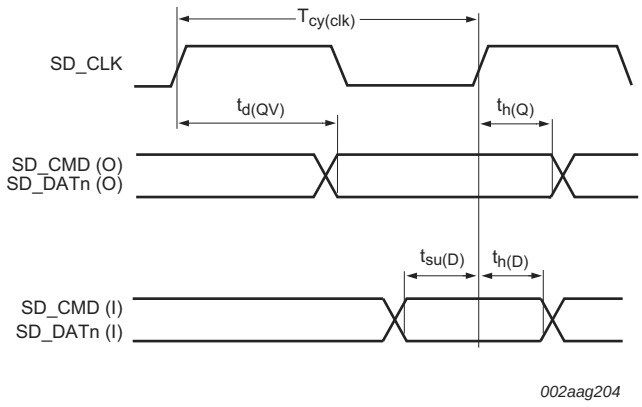


Fig 40. SD/MMC timing

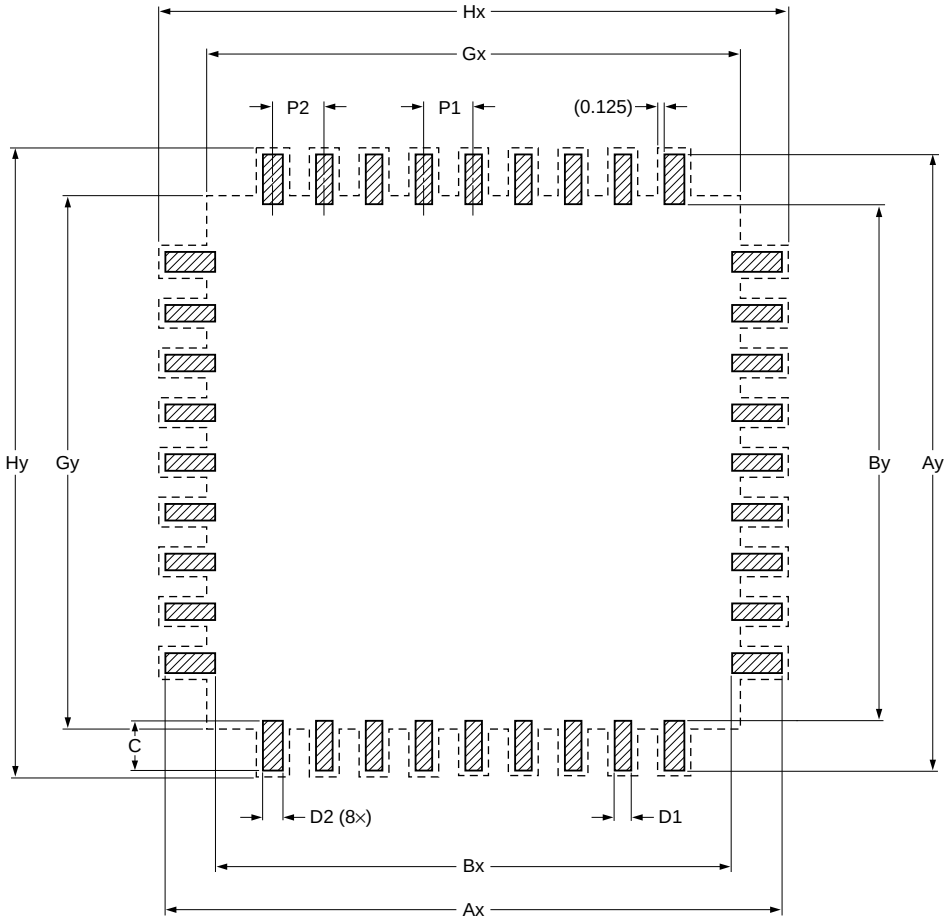
11.21 LCD

Table 38. Dynamic characteristics: LCD

T_{amb} = −40 °C to 105 °C; 2.4 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V; 2.7 V ≤ $V_{DD(IO)}$ ≤ 3.6 V; C_L = 20 pF. Simulated values.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{clk}	clock frequency	on pin LCD_DCLK	-	50	-	MHz
$t_{d(QV)}$	data output valid delay time		-	-	17	ns
$t_{h(Q)}$	data output hold time		8.5	-	-	ns

Footprint information for reflow soldering of LQFP208 package **SOT459-1**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

occupied area

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.500	0.560	31.300	31.300	28.300	28.300	1.500	0.280	0.400	28.500	28.500	31.550	31.550

sot459-1_fr

Fig 56. Reflow soldering of the LQFP208 package

Table 47. Revision history *…continued*

Document ID	Release date	Data sheet status	Change notice	Supersedes
Modifications:	• Parameter t_{ret} (retention time) for EEPROM updated in Table 15. • SGPIO and SPI location corrected in Figure 1. • SGPIO-to-DMA connection updated in Figure 6. • Parameter $V_{DDA(3V3)}$ added for pins USB0_VDDA3V3_DRIVER and USB0_VDDA3V3 in Table 11. • Parameter name $I_{DD(ADC)}$ changed to I_{DDA} in Table 11. • Minimum wake-up time from sleep mode added in Table 16. • Data for $I_{DD(IO)}$ added in Table 11. • Corrected max voltage on pins USB0_DP, USB0_DM, USB0_VBUS, USB1_DP, and USB1_DM in Table 7 and Table 11 to be consistent with USB specifications. • SPI and SGPIO peripheral power consumption added in Table 12. • SPI timing characteristics added. See Section 11.12. • SGPIO timing characteristics added. See Section 11.15. • Data sheet status changed to Product data sheet. • Conditions RPHASE1 and RPHASE2 corrected in Table 15 “EEPROM characteristics”. RPHASE1: t_{wait} > 70 ns. RPHASE2: t_{wait} > 35 ns. • $I_{DD(REG)(3V3)}$ updated in Table 11 “Static characteristics” for the following conditions: – Active mode: CCLK = 12 MHz; $I_{DD(REG)(3V3)}$ changed from 9.3 mA to 10 mA. – Active mode: CCLK = 60 MHz; $I_{DD(REG)(3V3)}$ changed from 26 mA to 28 mA. – Active mode: CCLK = 120 MHz; $I_{DD(REG)(3V3)}$ changed from 46 mA to 51 mA. – Active mode: CCLK = 180 MHz; $I_{DD(REG)(3V3)}$ changed from 66 mA to 74 mA. – Active mode: CCLK = 204 MHz; $I_{DD(REG)(3V3)}$ changed from 75 mA to 83 mA. – Sleep mode: CCLK = 12 MHz; $I_{DD(REG)(3V3)}$ changed from 6.2 mA to 8.8 mA. • Power consumption data in Figure 11 to Figure 14 updated. • IRC specifications corrected in Table 19 “Dynamic characteristic: IRC oscillator”. Accuracy changed to +/- 3 % over the entire temperature range. • SPIFI timing diagram corrected and specified for mode 0. See Table 27. • Table 21 “Dynamic characteristic: I/O pins[1]” added. • Parameter C_I corrected for high-drive pins (changed from 2 pF to 5.2 pF). See Table 11. • Internal pull-up resistor configuration added for $\overline{\text{RESET}}$, WAKEUPn, and ALARM pins. See Table 3. • Description of DEBUG pin updated. • Input range for PLL1 corrected: 1 MHz to 25 MHz. See Section 7.23.7 “System PLL1”. • Signal polarity of EMC_CKEOUT and EMC_DQMOUT corrected. Both signals are active HIGH. • SPIFI output timing parameters in Table 27 corrected to apply to Mode 0: – $t_{v(Q)}$ changed to 3.2 ns. – $t_{h(Q)}$ changed to 0.2 ns,		

Table 47. Revision history *…continued*

Document ID	Release date	Data sheet status	Change notice	Supersedes
Modifications:	• SD/MMC timing data updated. See Table 35 “Dynamic characteristics: SD/MMC”. • IEEE standard 802.3 compliance added to Section 11.18. Covers Ethernet dynamic characteristics of ENET_MDIO and ENET_MDC signals. • SSP master mode timing diagram updated with SSEL timing parameters. See Figure 31 “SSP in SPI mode and SPI master timing”. • Parameters t_{lead}, t_{lag}, and t_d added in Table 25 “Dynamic characteristics: SSP pins in SPI mode”. • Parameter t_{CSLWEL} with condition PB = 1 corrected: (WAITWEN + 1) × $T_{cy(clk)}$ added. See Table 29 “Dynamic characteristics: Static asynchronous external memory interface”. • Parameter $t_{CSLBLSL}$ with condition PB = 0 corrected: (WAITWEN + 1) × $T_{cy(clk)}$ added. See Table 29 “Dynamic characteristics: Static asynchronous external memory interface”. • Removed restriction on C_CAN bus usage. See CAN.1 errata in Ref. 2. • General-purpose OTP size corrected.			
LPC435X_3X_2X_1X v.3	20121206	Preliminary data sheet	-	LPC4357_53_37_33 v.2.1
Modifications:	• TFBGA180 packages removed. • Part LPC432x and LPC431x added. • SCT dither engine added and SCT bi-directional event enable features added. • Figure 10 “Dual-core debug configuration” added. • T = 105 °C data added in Figure 20 to Figure 23. • Change symbol names and parameter names in Table 21. • Parameter I_{LH} updated for condition V_I = 5 V and T_{amb} = 25 °C/105 °C in Table 11. • Power consumption data added in Section 10.1. • SPIFI dynamic characteristics added in Section 11.16. • IRC accuracy corrected to ± 2 % for T_{amb} = -40 °C to 0 °C and T_{amb} = 85 °C to 105 °C. • Pull-up and Pull-down current data (Figure 24 and Figure 25) updated with data for T_{amb} = 105 °C. • SPIFI maximum data rate changed to 52 MB per second. • Recommendation for V_{BAT} use added: The recommended operating condition for the battery supply is $V_{DD(REG)(3V3)} > V_{BAT}$ + 0.2 V. • Table 14 “Band gap characteristics” added. • Section 7.23.9 “Power Management Controller (PMC)” added. • Description of ADC pins on digital/analog input pins changed. Each input to the ADC is connected to ADC0 and ADC1. See Table 3. • OTP memory size changed to 64 bit. • Use of C_CAN peripheral restricted in Section 2. • ADC channels limited to a total of 8 channels shared between ADC0 and ADC1.			
LPC4357_53_37_33 v.2.1	20120904	Preliminary data sheet	-	LPC4357_53_37_33 v.2
Modifications:	• SSP0 boot pin functions corrected in Table 5 and Table 4. Pin P3_3 = SSP0_SCK, pin P3_6 = SSP0_SSEL, pin P3_7 = SSP0_MISO, pin P3_8 = SSP0_MOSI. • SWD removed for ARM Cortex-M0. • BOD de-assertion levels added in Table 13. • Peripheral power consumption data added in Table 12. • Minimum value for all supply voltages changed to -0.5 V in Table 7.			